AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A composite material, which is a Mo-Cu based composite material having a Cu content of 30 to 70 weight % and which comprises a Mo-Cu composite phase and at least one copper pool phase, said at least one copper pool phase being contained in an amount of 10 to 50 weight %, wherein said at least one copper pool phase has a grain size larger than ~~the~~ molybdenum particles forming the Mo-Cu composite phase and an average short diameter of 50 to 200 μm.

2. (cancelled)

3. (original): The composite material according to claim 1, wherein said composite material is subjected to plastic deformation.

4. (currently amended): A member using the composite material according to any one of claims 1 ~~to~~ and 3.

5. (currently amended): A heat-sink member using the composite material according to any one of claims 1 ~~to~~ and 3.

6. (previously presented): A method of producing a composite material, comprising the step of compressing a matrix of Mo powder and a copper-based material having an average short diameter of 50 μm or more and arranged in said matrix to obtain a compressed body and, optionally, sintering said compressed body to obtain a pre-sintered body, and the step of infiltrating one of copper and a copper alloy into said compressed body or said pre-sintered body to produce a composite material having a Cu content of 30 to 70 weight % and containing 10-50 weight % of at least one copper pool phase.

7. (original): The method according to claim 6, wherein the copper-based material is powder which has an average short diameter of 50 to 200 μm and which is mixed with said Mo powder before the compressing step.

8. (original): A semiconductor apparatus using the heat-sink member according to claim 5.

9. (cancelled)